

GaAs PHEMT MMIC MEDIUM POWER AMPLIFIER, 6.5 - 13.5 GHz

Typical Applications

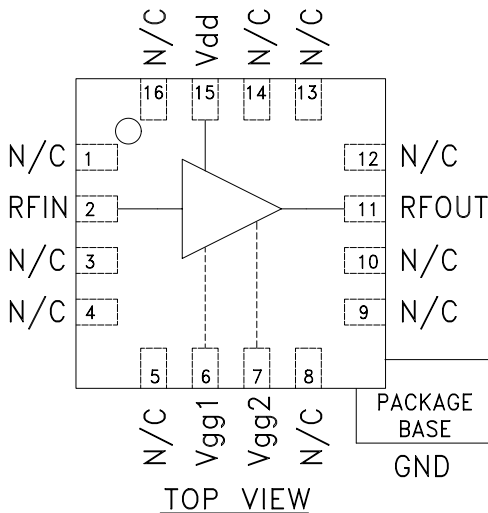
The HMC441LP3 is a medium PA for:

- Point-to-Point Radios
- Point-to-Multi-Point Radios
- VSAT
- LO Driver for HMC Mixers
- Military EW & ECM

Features

- Gain: 14 dB
- Saturated Power: +20 dBm @ 20% PAE
- Single Supply Voltage: +5.0 V w/ Optional Gate Bias
- 50 Ohm Matched Input/Output
- 3 x 3 x 1 mm QFN SMT Package

Functional Diagram



Vgg1, Vgg2: Optional Gate Bias

General Description

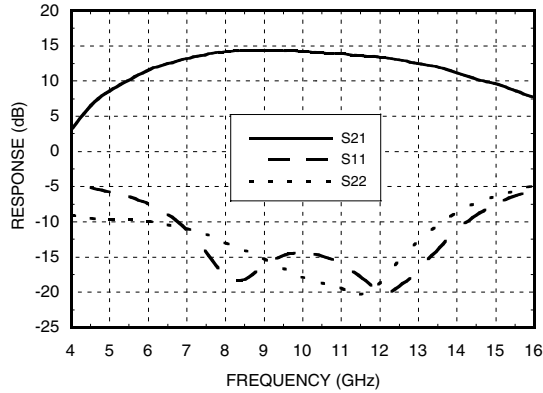
The HMC441LP3 is a broadband GaAs PHEMT MMIC Medium Power Amplifier which operates between 6.5 and 13.5 GHz. The leadless plastic QFN surface mount packaged amplifier provides 14 dB of gain, +20 dBm saturated power at 20% PAE from a +5.0 V supply voltage. An optional gate bias is provided to allow adjustment of gain, RF output power, and DC power dissipation. This 50 Ohm matched amplifier does not require any external components making it an ideal linear gain block or driver for HMC SMT mixers.

Electrical Specifications, $T_A = +25^\circ C, V_{dd1} = V_{dd2} = 5V, V_{gg1} = V_{gg2} = Open$

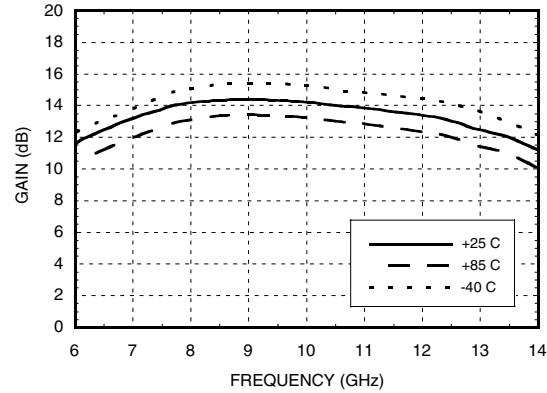
Parameter	Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Units
Frequency Range	6.5 - 8.0			8.0 - 11.0			11.0 - 13.5			GHz
Gain	10	13		12	14		10	13		dB
Gain Variation Over Temperature		0.02	0.025		0.02	0.025		0.02	0.025	dB/ °C
Input Return Loss		12			15			14		dB
Output Return Loss		12			15			13		dB
Output Power for 1 dB Compression (P1dB)	13	16		15	18		14	17		dBm
Saturated Output Power (Psat)		18.5			20			19.5		dBm
Output Third Order Intercept (IP3)	23	26		26	29		26	29		dBm
Noise Figure		5.0			4.5			4.75		dB
Supply Current (Idd)		80			80			80		mA

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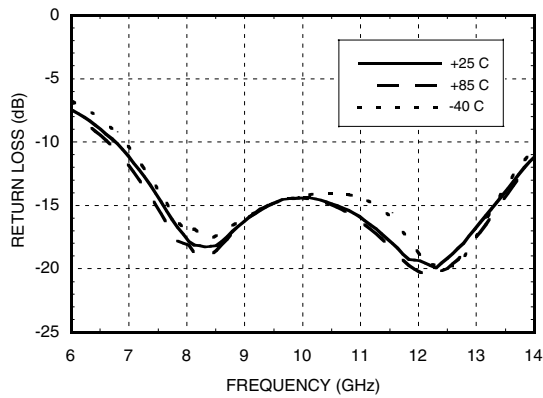
Broadband Gain & Return Loss



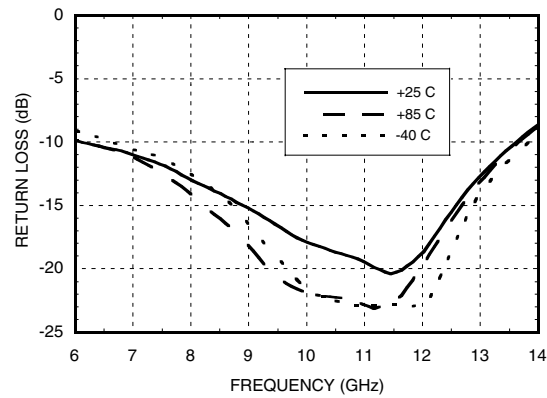
Gain vs. Temperature



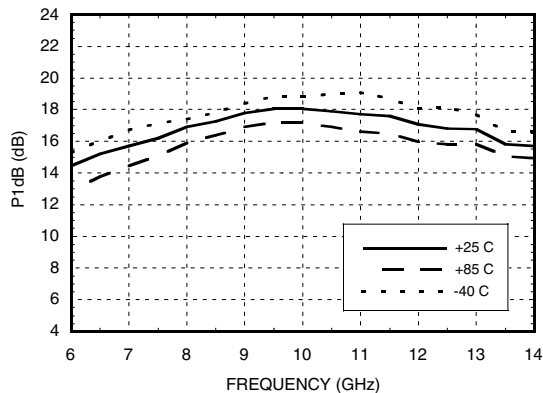
Input Return Loss vs. Temperature



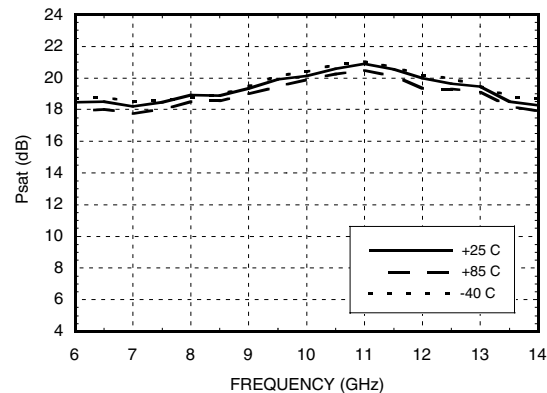
Output Return Loss vs. Temperature



P1dB vs. Temperature

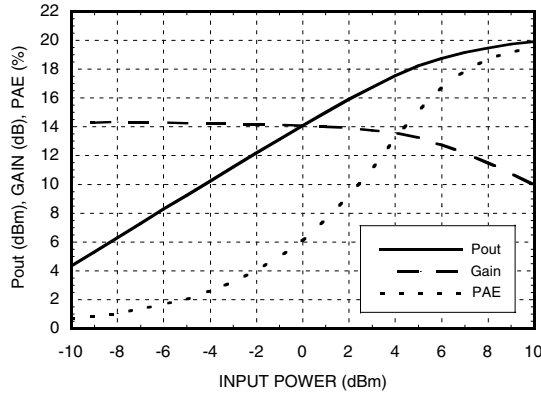


Psat vs. Temperature

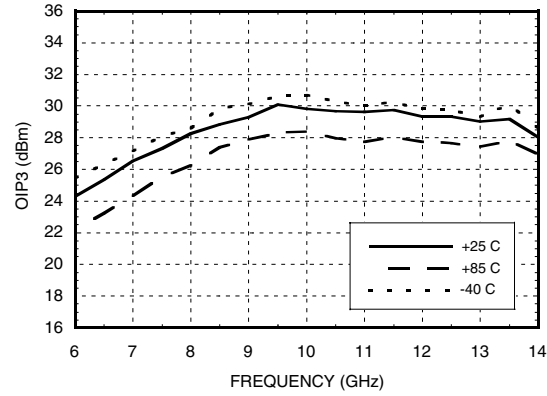


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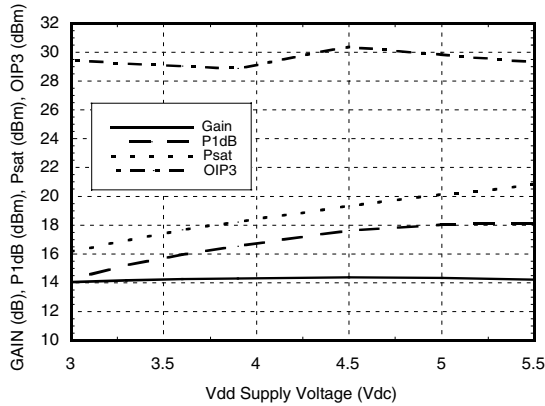
Power Compression @ 10 GHz



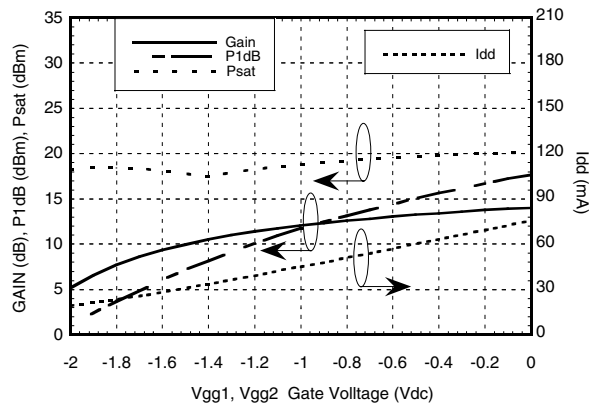
Output IP3 vs. Temperature



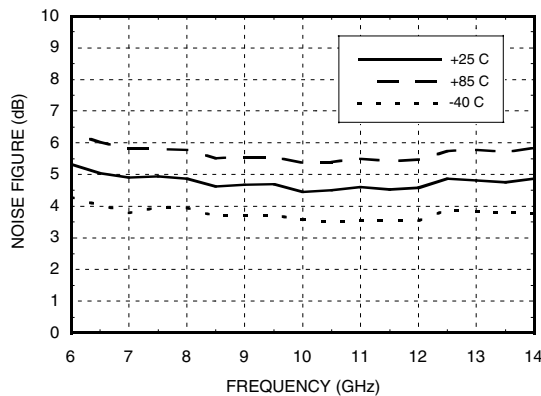
Gain, Power & OIP3 vs. Supply Voltage @ 10 GHz



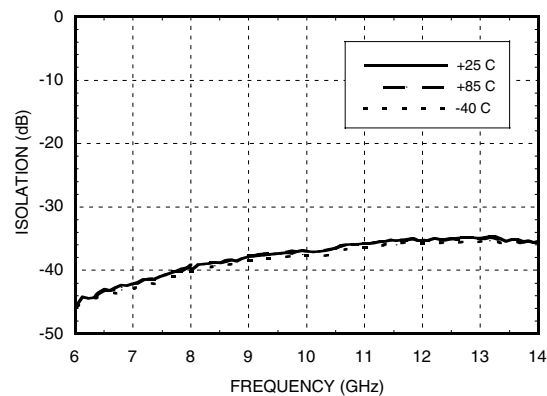
Gain, Power & Idd vs. Gate Voltage @ 10 GHz



Noise Figure vs. Temperature



Reverse Isolation vs. Temperature



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Absolute Maximum Ratings

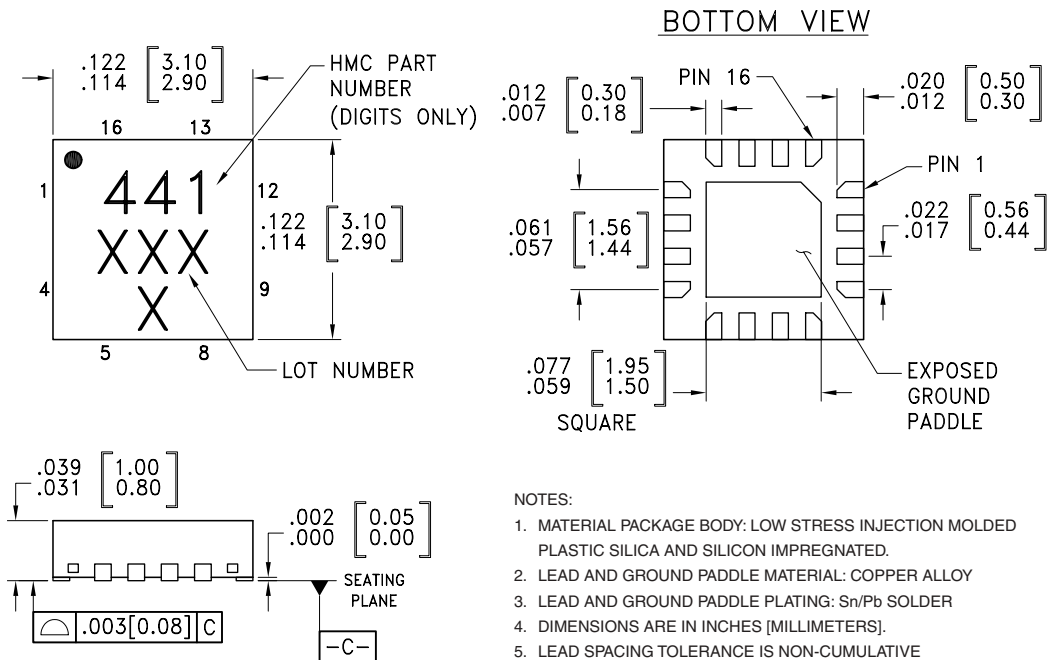
Supply Voltage (Vdd)	6.0 Vdc
Gate Bias Voltage (Vgg 1,2)	-8 to 0 Vdc
Input Power (RFin)	+20 dBm
Channel Temperature	175 °C
Continuous Pdiss (T= 85 °C) (derate 5.35 mW/°C above 85 °C)	0.481 W
Storage Temperature	-65 to +150° C
Operating Temperature	-40 to +85° C

Typical Supply Current vs. Vdd

Vdd (V)	Idd (mA)
+5.5	81
+5.0	80
+4.5	79
+3.3	72
+3.0	71

Note: Amplifier will operate over full voltage range shown above

Outline Drawing

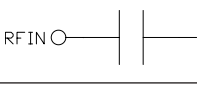
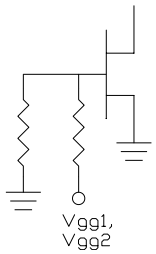
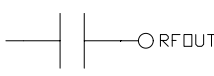
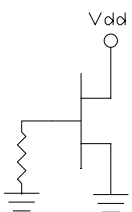



NOTES:

1. MATERIAL PACKAGE BODY: LOW STRESS INJECTION MOLDED PLASTIC SILICA AND SILICON IMPREGNATED.
2. LEAD AND GROUND PADDLE MATERIAL: COPPER ALLOY
3. LEAD AND GROUND PADDLE PLATING: Sn/Pb SOLDER
4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
5. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
6. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
7. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
8. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

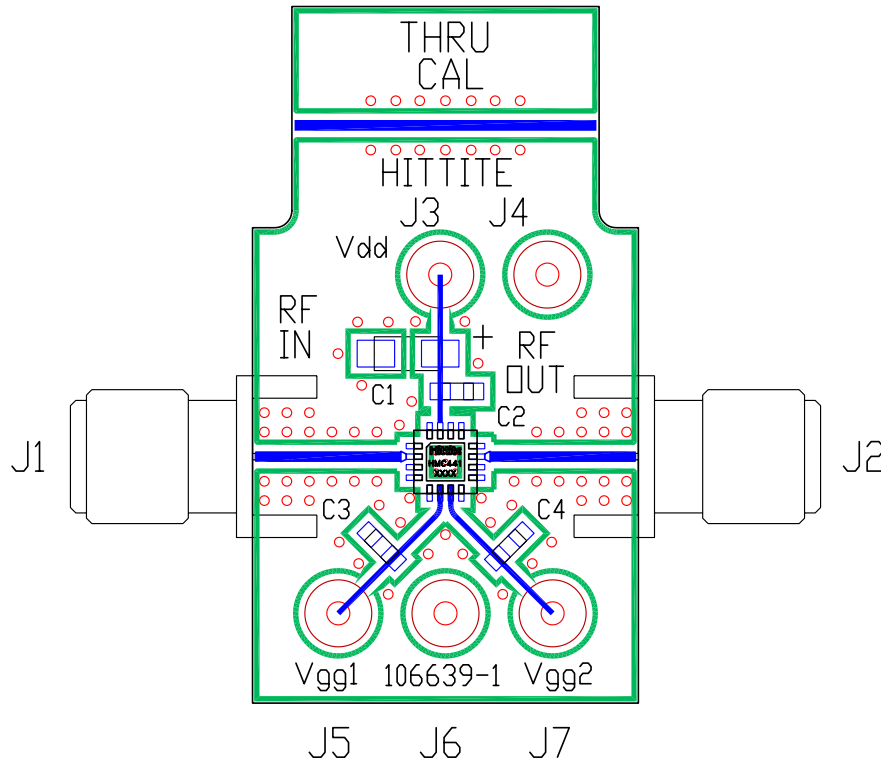
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Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 3-5, 8-10, 12-14, 16	N/C	This pin may be connected to RF/DC ground.	
2	RF IN	This pin is AC coupled and matched to 50 Ohms from 6.5 - 13.5 GHz.	
6, 7	Vgg1, Vgg2	Optional gate control for amplifier. If left open, the amplifier will run at standard current. Negative voltage applied will reduce current.	
11	RF OUT	This pin is AC coupled and matched to 50 Ohms from 6.5 - 13.5 GHz.	
15	Vdd	Power Supply Voltage for the amplifier. An external bypass capacitor of 100 pF is required.	
	GND	Package bottom must be connected to RF/DC ground.	

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Evaluation PCB



List of Material

Item	Description
J1 - J2	PC Mount SMA Connector
J3 - J7	DC Pin
C1	4.7 μ F Capacitor, Tantalum
C2 - C4	100 pF Capacitor, 0402 Pkg.
U1	HMC441LP3 Amplifier
PCB*	106639 Evaluation PCB, 10 mils
* Circuit Board Material: Rogers 4350	

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of VIA holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.